

Title (en)
ELECTRONIC ASSEMBLY AND METHOD FOR THE PRODUCTION THEREOF

Title (de)
ELEKTRONISCHE KOMPONENTE UND VERFAHREN ZU DEREN HERSTELLUNG

Title (fr)
COMPOSANT ÉLECTRONIQUE ET SON PROCÉDÉ DE FABRICATION

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Abstract (en)
[origin: WO2016128244A1] The invention relates to an electronic assembly (E) comprising: a carrier element (1), a circuit carrier (3) having a number of electronic components (4), a circuit board (6), which is electrically conductively connected to the circuit carrier (3), and a covering element (2) for covering the circuit carrier (3), the covering element (2) being arranged on one flat side of the circuit board (6) and the carrier element (1) being arranged on an opposite flat side of the circuit board (6). According to the invention, the circuit board (6) is welded respectively to the carrier element (1) and to the covering element (2). The invention further relates to a method for producing such an electronic assembly (E).

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C-Set (source: EP US)
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See references of WO 2016128244A1

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